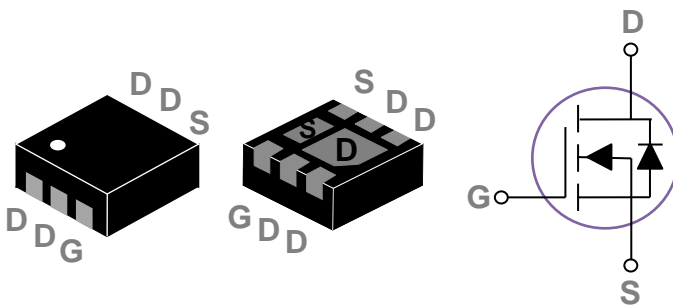


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN2x2-6L 2EP Pin Configuration



BVDSS	RDSON	ID
30V	13mΩ	10A

Features

- 30V, 10A, $R_{DS(ON)} = 13m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_A=25^\circ C$)	10	A
	Drain Current – Continuous ($T_A=70^\circ C$)	8	A
I_{DM}	Drain Current – Pulsed ¹	40	A
EAS	Single Pulse Avalanche Energy ²	13	mJ
IAS	Single Pulse Avalanche Current ²	16	A
P_D	Power Dissipation ($T_A=25^\circ C$)	2.01	W
	Power Dissipation – Derate above $25^\circ C$	0.016	W/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.04	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V, T _J =25°C	---	---	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	---	---	10	μA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} =10V, I _D =6A	---	10.2	13	mΩ
		V _{GS} =4.5V, I _D =4A	---	13.3	18	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	1.2	1.8	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4	---	mV/°C
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =3A	---	6	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{3, 4}	V _{DS} =15V, V _{GS} =10V, I _D =5A	---	10.7	16	nC
Q _{gs}	Gate-Source Charge ^{3, 4}		---	1.7	2.6	
Q _{gd}	Gate-Drain Charge ^{3, 4}		---	2.5	5	
T _{d(on)}	Turn-On Delay Time ^{3, 4}	V _{DD} =15V, V _{GS} =10V, R _G =6Ω I _D =5A	---	3.8	6	ns
T _r	Rise Time ^{3, 4}		---	10	15	
T _{d(off)}	Turn-Off Delay Time ^{3, 4}		---	22	33	
T _f	Fall Time ^{3, 4}		---	6.6	10	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	750	1150	pF
C _{oss}	Output Capacitance		---	120	180	
C _{rss}	Reverse Transfer Capacitance		---	90	140	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.8	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	10	A
I _{SM}	Pulsed Source Current ³		---	---	20	A
V _{SD}	Diode Forward Voltage ³	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	V _R =30V, I _S =10A	---	120	---	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs, T _J =25°C	---	175	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=16A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

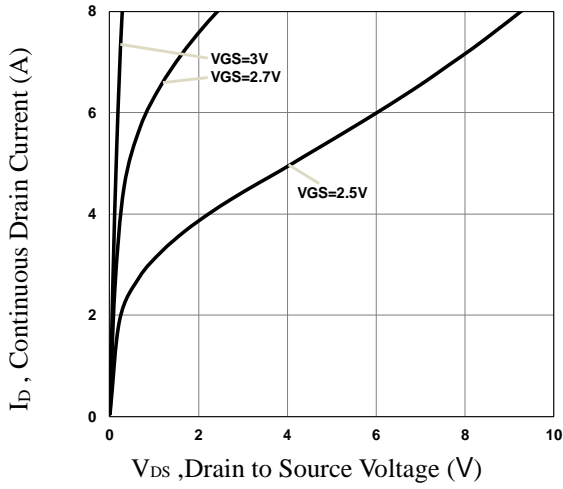


Fig.1 Typical Output Characteristics

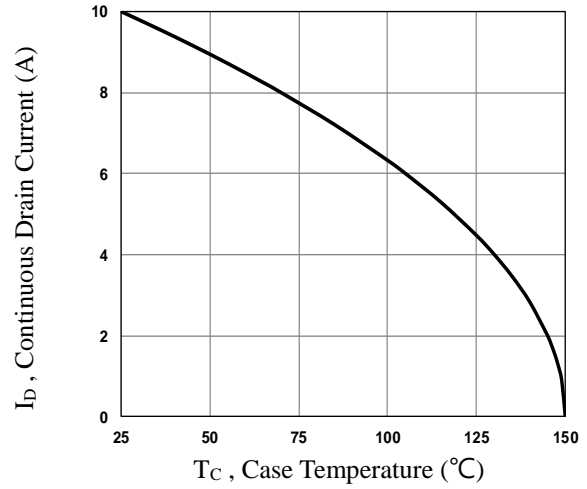


Fig.2 Continuous Drain Current vs. T_c

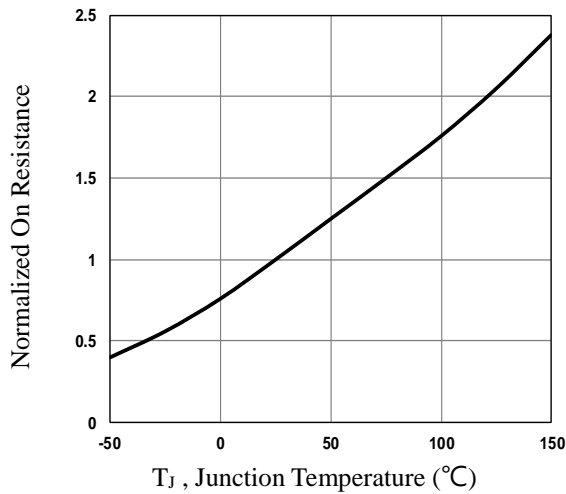


Fig.3 Normalized $R_{DS(on)}$ vs. T_j

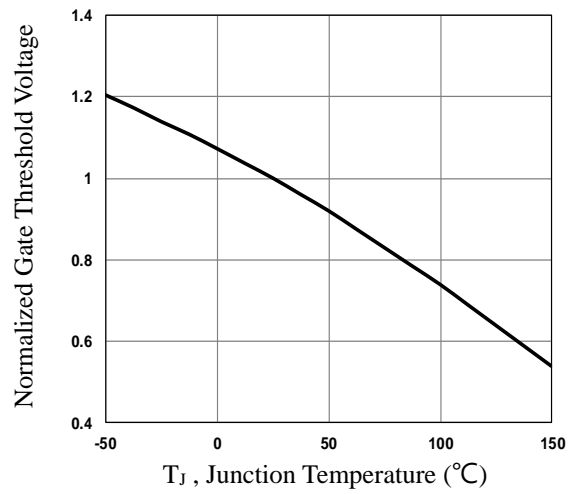


Fig.4 Normalized V_{th} vs. T_j

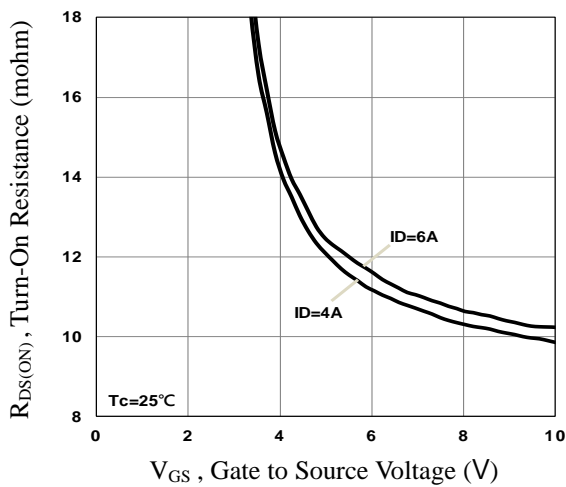


Fig.5 Turn-On Resistance vs. V_{GS}

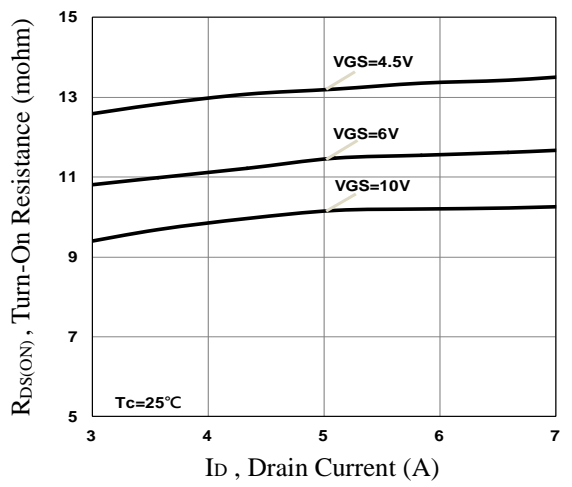


Fig.6 Turn-On Resistance vs. I_D

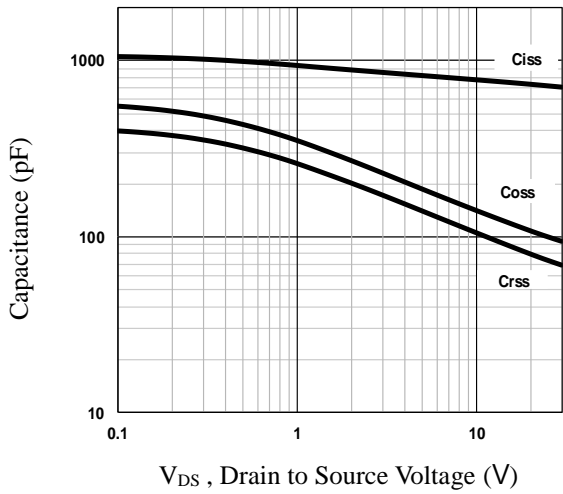


Fig.7 Capacitance Characteristics

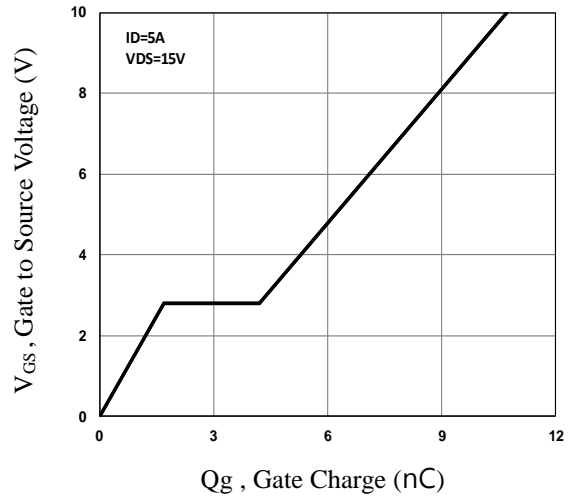


Fig.8 Gate Charge Characteristics

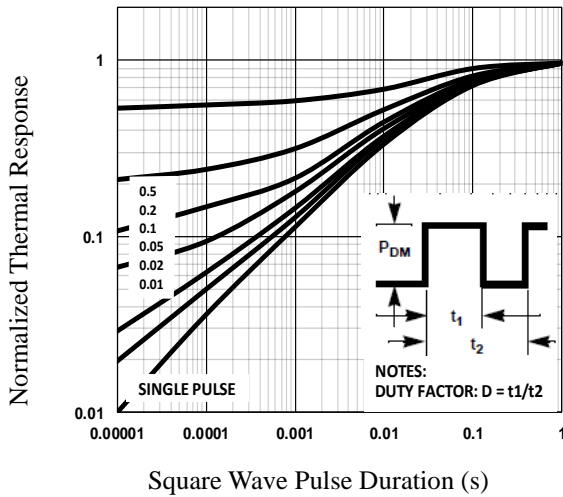


Fig.9 Normalized Transient Impedance

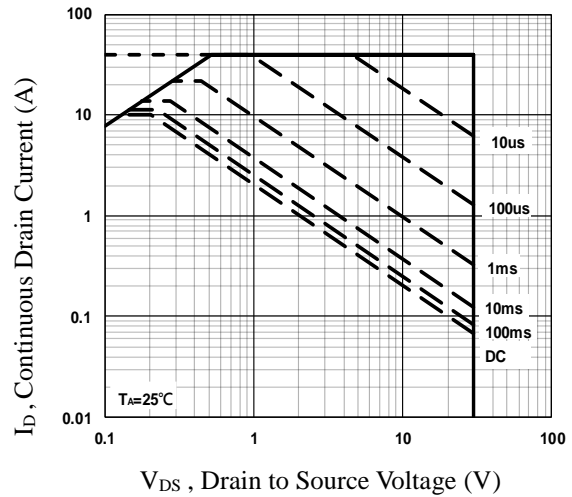


Fig.10 Maximum Safe Operation Area

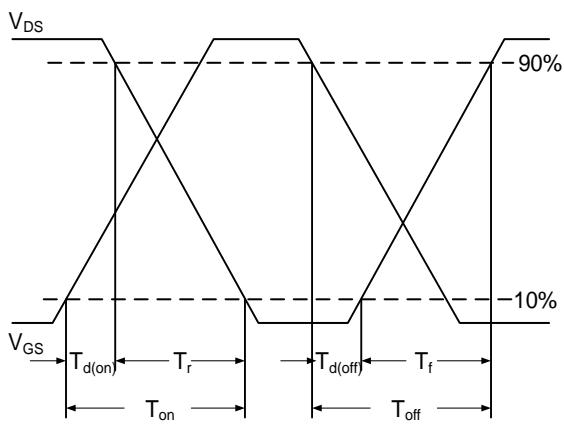


Fig.11 Switching Time Waveform

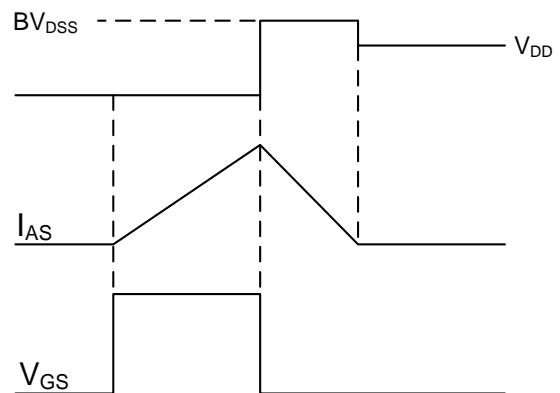
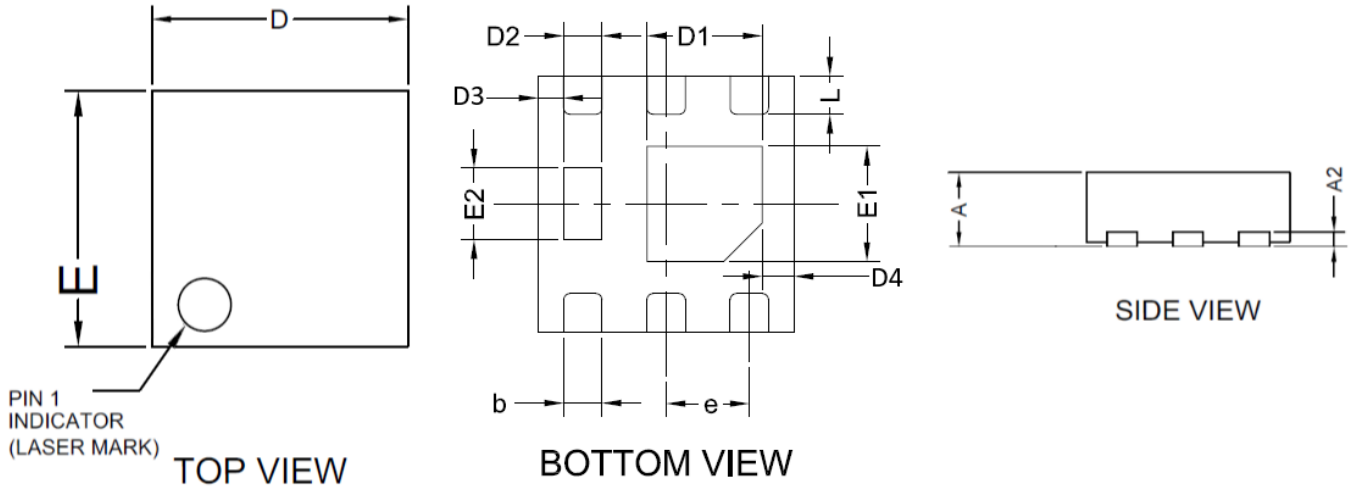


Fig.12 EAS Waveform

DFN2x2-6L 2EP PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.500	0.031	0.019
A2	0.250	0.145	0.010	0.006
b	0.350	0.250	0.014	0.010
D	2.100	1.900	0.083	0.075
D1	1.000	0.800	0.040	0.031
D2	0.350	0.250	0.014	0.010
D3	0.200BSC		0.008BSC	
D4	0.200BSC		0.008BSC	
E	2.100	1.900	0.083	0.075
E1	1.050	0.800	0.041	0.031
E2	0.66	0.46	0.026	0.018
e	0.650BSC		0.026BSC	
L	0.350	0.250	0.014	0.010

DFN2x2-6L 2EP RECOMMENDED LAND PATTERN

